2SB1320A

Silicon PNP epitaxial planar type

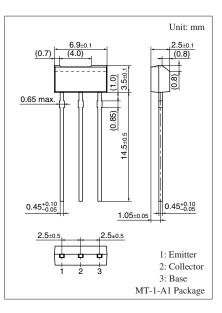
For general amplification Complementary to 2SD1991A

Features

- \bullet High forward current transfer ratio $h_{F\!E}$
- Allowing supply with the radial taping

3 - a								
Parameter	Symbol	Rating	Unit					
Collector-base voltage (Emitter open)	V _{CBO}	-60	V					
Collector-emitter voltage (Base open)	V _{CEO}	-50	V					
Emitter-base voltage (Collector open)	V _{EBO}	-7	V					
Collector current	I _C	-100	mA					
Peak collector current	I _{CP}	-200	mA					
Collector power dissipation	P _C	400	mW					
Junction temperature	Tj	150	°C					
Storage temperature	T _{stg}	-55 to +150	°C					





Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

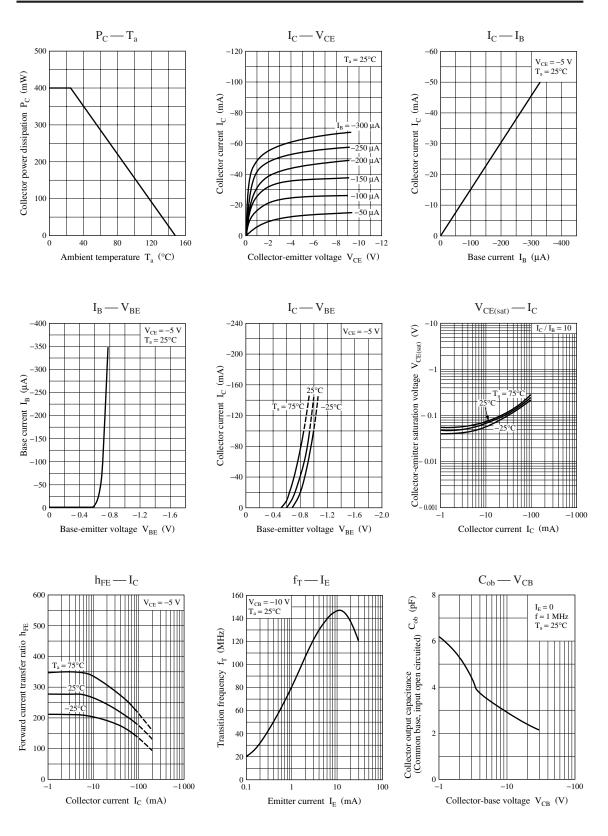
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$	-60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = -10 \ \mu A, \ I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -20 \text{ V}, I_E = 0$			-1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -20 \text{ V}, I_B = 0$			-1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = -10 \text{ V}, I_C = -2 \text{ mA}$	160		460	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -10 \text{ mA}$			-1	V
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		3.5		pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

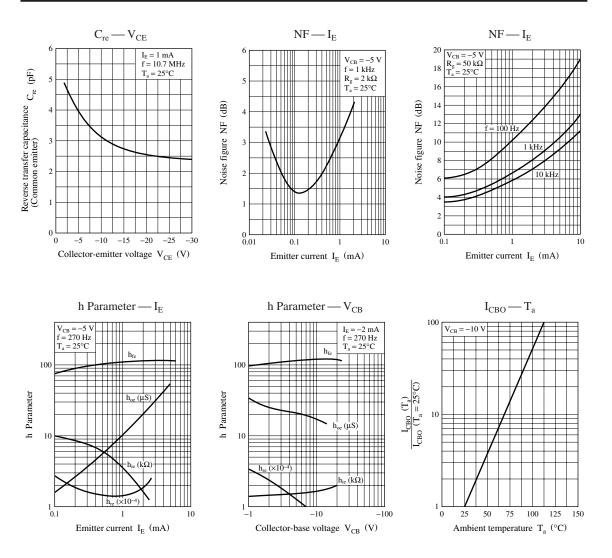
2. *: Rank classification

Rank	Q	R	S	No-rank
$h_{\rm FE}$	160 to 260	210 to 340	290 to 460	160 to 460

Product of no-rank is not classified and have no marking symbol for rank.



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